CRMGGH0804B

N-Channel 80V, 4.4mΩ Typ. Power MOSFET

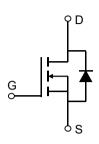
Description

Features

• 80V, 105A

 $R_{DS(ON)}$ Typ = 4.4m Ω @ V_{GS} = 10V

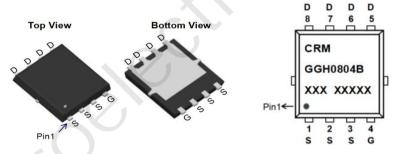
- Advanced Split Gate Trench Technology
- Excellent R_{DS(ON)} and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔVds TESTED!





Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMGGH0804B	CRMGGH0804B	PDFN5x6-8L	TAPING	13"	5000	60000

Absolute Maximum Ratings (@ $T_J = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		80	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	T _C = 25°C	105	Α
I _D	Continuous Drain Current	T _C = 100°C	63	Α
I _{DM}	Pulsed Drain Current (1)		420	Α
E _{AS}	Single Pulsed Avalanche Energy (2)		240	mJ
P_{D}	Power Dissipation	T _C = 25°C	113	W
$R_{ heta JC}$	Thermal Resistance, Junction to Case		1.1	°C/W
T_{J}, T_{STG}	Junction & Storage Temperature Range		-55 to 150	°C

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Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
		Conditions	IVIIII.	ıyρ.	IVIAA.	Offic
	acteristics					
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0V$	80	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 80V, V_{GS} = 0V$	-	-	1.0	μА
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics				<u></u>	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2	3	4	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10V, I_D = 20A$	-	4.4	5.7	mΩ
Dynamic	Characteristics					
C _{iss}	Input Capacitance		-	3468	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = 40V,$ f = 1MHz	-	660	-	pF
C_{rss}	Reverse Transfer Capacitance	I – TIVIMZ	X -	12.5	-	pF
Q _q	Total Gate Charge		-	48	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0$ to 10V	\mathcal{O}_{\perp}	15	-	nC
Q_{gd}	Gate Drain("Miller") Charge	$V_{DS} = 40V, I_{D} = 55A$	-	13.5	-	nC
Switchin	g Characteristics					
t _{d(on)}	Turn-On DelayTime		-	16	-	ns
t _r	Turn-On Rise Time	$V_{GS} = 10V, V_{DD} = 40V$	-	15	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 55A, R_{GEN} = 1.6\Omega$	-	40	-	ns
t _f	Turn-Off Fall Time		_	12	-	ns
Drain-So	urce Diode Characteristics and M	Max Ratings				
I _S	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	105	Α
I _{SM}	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	420	Α
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 20A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	40	-	ns
Qrr	Body Diode Reverse Recovery Charge	$I_F = 30A$, di/dt = 100A/us	_	165	_	nC
σ	222, 2.200 (Cooled (Cooled)) Only					

Notes:

^{1.} Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

^{2.} E_{AS} condition: Starting T_J =25°C, V_{DD} =40V, V_G =10V, R_G =25ohm, L=0.5mH, I_{AS} =31A

^{4.} Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

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Test Circuit

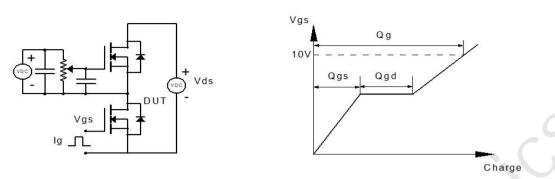


Figure 1: Gate Charge Test Circuit & Waveform

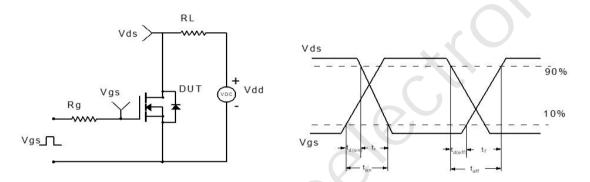


Figure 2: Resistive Switching Test Circuit & Waveform

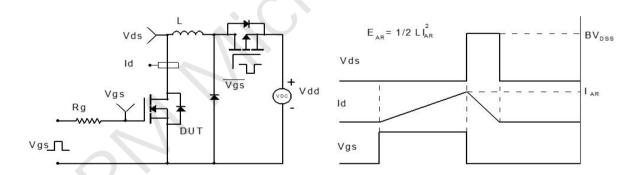


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

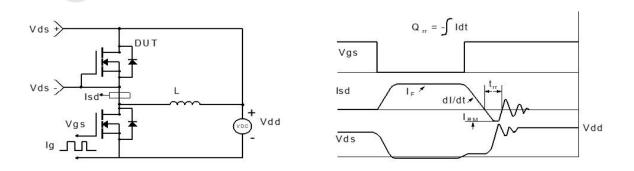
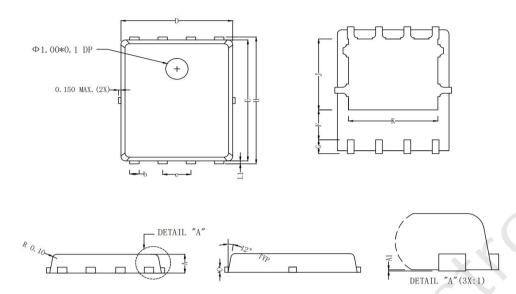


Figure 4: Diode Recovery Test Circuit & Waveform

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Package Mechanical Data(PDFN5x6-8L)



Dimensions In Millimeterer					
Symbol	MIN	TYP	MAX		
A	0.90	1.00	1.10		
A1	0.00	0.03	0.05		
b	0. 25	0.35			
C	0. 254 REF				
D	4.80	4.90	5.00		
F	1.35 REF				
Е	5. 65 5. 75		5.85		
e	1.27 BSC				
Н	5. 90	6.00	6. 10		
L1	0.10	0.13	0.16		
G	0.55 REF				
K	4.00 REF				
J	3.45 REF				

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